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(54) Title: BONDING STRESS TESTING ARRANGEMENT AND METHOD OF DETERMINING STRESS

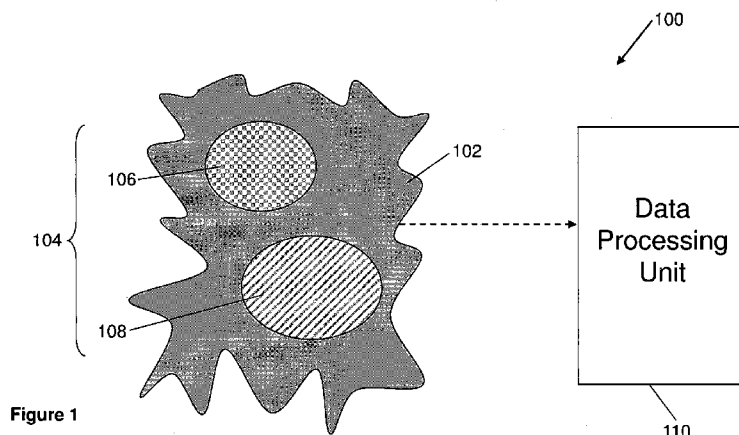


Figure 1

(57) Abstract: A bonding stress testing arrangement and a method of determining stress are provided. The bonding stress testing arrangement includes at least one bond pad; a sensor assembly comprising any one of a first sensor arrangement, a second sensor arrangement and a combination of the first sensor arrangement and the second sensor arrangement; wherein the first sensor arrangement is adapted to measure an average stress on a portion of a bonding area under the at least one bond pad, and the second sensor arrangement is adapted to determine stress distribution over a portion or an entire of the bonding area under the at least one bond pad.